

TechConnect Ventures

Sprint Challenge Brief:

Materials for Improved Cold Storage and Transportation of Perishables

BACKGROUND

In support of several packaging companies, TechConnect Ventures is seeking responses describing materials which exhibit superior insulative properties. Whether for transporting food, pharmacological substances or organs for transplant, it is vital that the contents in the package remain cold. Insulation, commonly in the form of a foamed solid such as polystyrene, reduces heat transfer from the colder item to the warmer environment. The clients seek new and innovative materials with low thermal conductivity that are suitable for usage in packaging applications.

The goal of this sprint is to facilitate contact and interactions between the Sprint sponsor and active researchers or technology developers in this space. Submissions and novel concepts from individuals and organizations in academia and research are of significant interest, but all viable technology providers are invited to respond for potential commercial opportunities with the client.

AREAS OF INTEREST

Our clients are interested in all insulative materials. Relevant areas of interest include, but are not limited to:

- New materials for usage in foamed-type insulation
- Bio-inspired materials such as keratin
- Carbon composites
- Silica fibers
- Insulative paint or coatings
- Nano-ceramics

BUSINESS OPPORTUNITY FOR SOLVERS

All complete and eligible Entries will be included in our exclusive Innovation Opportunity Report that will be presented to the innovation-seeking clients and partners. Solvers with well-matched capabilities may be contacted directly by consortium members to discuss potential partnership opportunities. Top-rated Entries may also be invited to register or participate in an upcoming TechConnect Ventures event or pitch program.

PARTICIPATION RULES & GUIDELINES

1. You must complete the provided Submission webform on the Sprint Submission page.
2. You are encouraged to submit a short presentation or pitch deck. A template is available on the Submission page.
3. **DO NOT INCLUDE ANY INFORMATION MARKED CONFIDENTIAL, PROPRIETARY, SENSITIVE OR CLASSIFIED. SUBMISSIONS MARKED AS SUCH WILL NOT BE SHARED WITH CLIENTS.**

Solvers should to review the [Rules](#) and [Guidelines](#) provided on the Sprint page for details about participation, including submission criteria, eligibility information, and more.

QUESTIONS? Contact Executive Director, Nick Kacsandi at info@techconnectventures.com